

3.5x2.8mm PLCC2 SMD LED

#### **Features**

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2000pcs/ Reel
- $\bullet$  MSL (Moisture Sensitivity Level): 3
- RoHS compliant

# Applications

- Backlighting for tell-tale indicators
- Dashboard lighting
- Interior lighting (footwell, dome light, accent lighting, etc.)
- Exterior lighting (turn signals, side markers, CHMSL, etc.)
- Signs and signals
- Various applications requiring high temperature rating

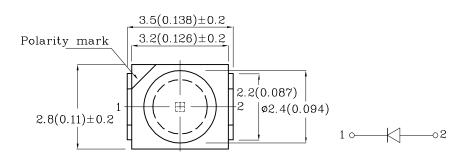


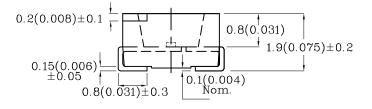




ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

# **Package Dimensions**





#### Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm$  0.25(0.01") unless otherwise noted.
- $3. \ {\rm Specifications}$  are subject to change without notice.

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## Part Number: XZYG45WTHTA



### 3.5x2.8mm PLCC2 SMD LED

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (IF=20mA) mcd		Viewing Angle 20 1/2	
				Code.	Min.	Max.	
				E*	12*	20*	
XZYG45WTHTA	Green	AlGaInP	Water Clear	F*	20*	40*	120°
			-	G*	40*	55*	

# Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Value	Unit
Power dissipation	PD	125	mW
Junction temperature	$\mathrm{T}\mathrm{J}$	115	°C
Reverse Voltage	VR	5	V
Operating Temperature	Тор	-40 To +100	°C
Storage Temperature	Tstg	-40 To +115	°C
DC Forward Current	$_{ m IF}$	50	mA
Peak Forward Current [2]	IFM	150	mA
Electrostatic Discharge Threshold (HBM)		3000	V
Thermal Resistance (Junction/ambient) [1]	Rth j-a	370	°C/W
Thermal Resistance (Junction / Solder point) [1]	Rth j-s	200	°C/W

- 1. Rth(j-a) Results from mounting on PC board FR4 (pad size≥16 mm² per pad),
- 2. 1/10 Duty Cycle, 0.1ms Pulse Width.
- 3. A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

# Electrical / Optical Characteristics at Ta=25°C

n .	G 1.1	Value				TI :	
`Parameter	Symbol	Code.	Min.	Typ.	Max.	Unit	
Wavelength at peak emission CIE127-2007* IF = 20mA	λpeak	-	1	560*	1	nm	
		0	556*	-	559*		
Dominant Wavelength CIE127-2007* IF = 20mA	λdom [1]	1	559*	-	561*	nm	
		2	561*	-	563*		
Spectral bandwidth at 50% Frel MAX $IF = 20mA$	λD	-	-	20	-	nm	
Forward Voltage IF = 20mA	VF [2]	-	-	2.2	2.5	V	
Reverse Current VR = 5V	Ir	-	-	-	10	μА	
Temperature coefficient of $\lambda$ peak IF = 20mA,-10°C $\leq$ T $\leq$ 100°C	ТС\peak	-	-	0.12	-	nm/°C	
Temperature coefficient of $\lambda$ dom IF = 20mA,-10°C $\leq$ T $\leq$ 100°C	TCλdom	-	-	0.08	-	nm/°C	
Temperature coefficient of VF $I_F = 20 mA, -10 ^{\circ}C \leq T \leq 100 ^{\circ}C$	TCv	-	-	-2.0	-	mV/°C	

#### Notes:

- 1. Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- $\mbox{*}$  Wavelength value is in accordance with CIE127-2007 standards.

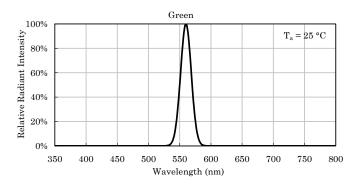
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Note:  $1.01/2 \ \text{is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.}$ 

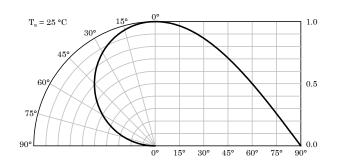
<sup>\*</sup>Luminous intensity value is in accordance with CIE127-2007 standards.





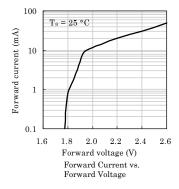


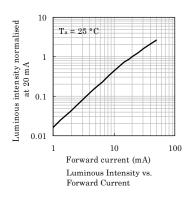
Relative Intensity Vs. CIE Wavelength

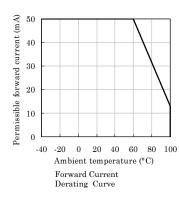


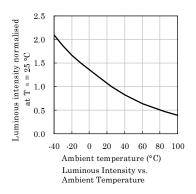
Spatial Distribution

### **❖** Green



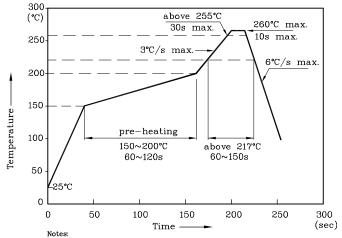






# LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)



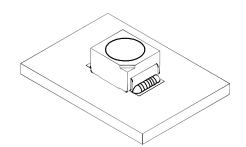
- 1. All temperatures refer to the center of the package, measured on the package body surface facing up during reflow.
- 2. Do not apply any stress to the LED during high temperature conditions.

  3. Maximum number of soldering passes: 2

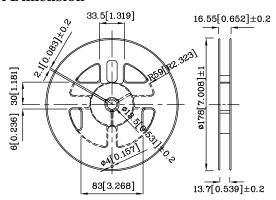




❖ The device has a single mounting surface. The device must be mounted according to the specifications.



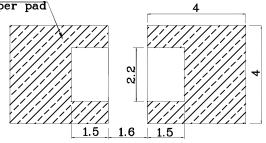
#### **❖** Reel Dimension



Recommended Soldering Pattern (Units: mm; Tolerance: ±0.1)

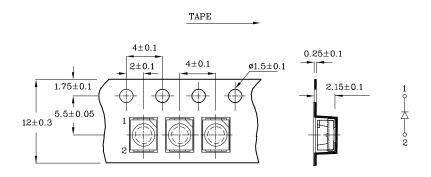
Pad design for improved heat dissipation Cu-area>16mm²





Solder resist

## \* Tape Specification (Units:mm)



### Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage:  $\pm -0.1$ V

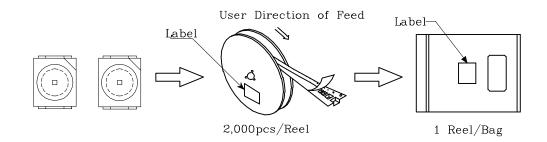
Note: Accuracy may depend on the sorting parameters.

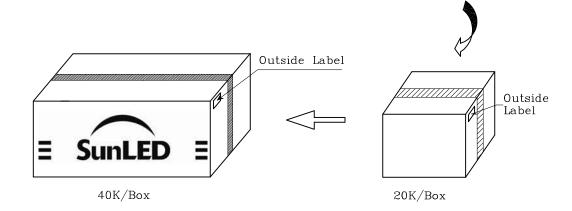
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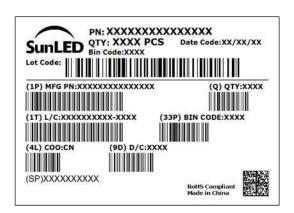




### PACKING & LABEL SPECIFICATIONS







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# **Reliability Test Items And Conditions**

The reliability of products shall be satisfied with items listed below

Lot Tolerance Percent Defective (LTPD): 10%

No.	Test Item	Standards	Test Condition	Test Times / Cycles	Number of Damaged
1	Continuous operating test	-	$T_a$ = 25°C, $I_F$ = maximum rated current *	1,000 h	0 / 22
2	High Temp. operating test	EIAJ ED-4701/100 (101)	$T_a$ = 100°C, $I_F$ = maximum rated current *	1,000 h	0 / 22
3	Low Temp. operating test	-	$T_a \!=$ -40°C, $I_F \!=$ maximum rated current *	1,000 h	0 / 22
4	High temp. storage test	EIAJ ED-4701/100 (201)	$T_a$ = maximum rated storage temperature	1,000 h	0 / 22
5	Low temp. storage test	EIAJ ED-4701/100 (202)	T <sub>a</sub> = -40°C	1,000 h	0 / 22
6	High temp. & humidity storage test	EIAJ ED-4701/100 (103)	$T_a = 60$ °C, RH = 90%	500 h	0 / 22
7	High temp. & humidity operating test	EIAJ ED-4701/100 (102)	$T_a$ = 60°C, RH = 90% $I_F$ = maximum rated current *	500 h	0 / 22
8	Soldering reliability test	EIAJ ED-4701/100 (301)	Moisture soak: 30°C, 70% RH, 72h Preheat: 150~180°C (120s max.) Soldering temp: 260°C(10s)	2 times	0 / 18
9	Thermal shock operating test	-	$T_a$ = -40°C(15min) ~ 100°C(15min) $I_F$ = derated current at 100°C	1,000 cycles	0 / 22
10	Thermal shock test	-	$T_a$ = -40°C(15min) ~ maximum rated Storage temperature(15min)	1,000 cycles	0 / 22
11	Electric Static Discharge (ESD)	EIAJ ED-4701/100 (304)	$C = 100 pF$ , $R2 = 1.5 K\Omega$ $V = 3000 V$	Once each Polarity	0 / 22
12	Vibration test	-	$a = 196 \text{m/s}^2$ , $f = 100 \sim 2 \text{KHz}$ , $t = 48 \text{min for all xyz axes}$	4 times	0 / 22

<sup>\*:</sup> Refer to forward current vs. derating curve diagram

# Criteria for Judging Damage

Items	Symbols	Conditions	Failure Criteria
luminous Intensity	lv	$I_F = 20 \text{mA}$	Testing Min. Value < Spec.Min.Value x 0.5
Forward Voltage	$V_{\rm F}$	$I_F = 20 \text{mA}$	Testing Max. Value $\geq$ Spec.Max.Value x 1.2
Reverse Current	IR	VR = Maximum Rated Reverse Voltage	Testing Max. Value $\geq$ Spec.Max.Value x 2.5
High temp. storage test	-	-	Occurrence of notable decoloration, deformation and cracking

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